

## Title (en)

METHOD AND DEVICE FOR MOUNTING ELECTRONIC COMPONENT ON CIRCUIT BOARD

## Title (de)

VERFAHREN UND VORRICHTUNG ZUM BEFESTIGEN VON EINEM ELEKTRONISCHEN BAUTEIL AUF EINER LEITERPLATTE

## Title (fr)

PROCEDE ET DISPOSITIF POUR MONTER DES COMPOSANTS ELECTRONIQUES SUR UNE PLAQUETTE DE CIRCUIT

## Publication

**EP 0954208 A4 20020911 (EN)**

## Application

**EP 97950421 A 19971226**

## Priority

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## Abstract (en)

[origin: EP0954208A1] When mounting an IC chip 1 on a circuit board 4, bumps 3 are formed on electrodes 2 on the IC chip, and the bumps and the electrodes of the circuit board are aligned in position with each other with interposition of an insulative thermosetting resin 6 having no conductive particle between the electrodes of the circuit board and the bumps. The IC chip is pressed against the circuit board with a pressure force of not smaller than 20 gf per bump by a heated head 8 so as to perform warp correction of the IC chip and the board, while the resin interposed between the IC chip and the circuit board is hardened to bond the IC chip and the circuit board together.

## IPC 1-7

**H05K 3/32**; **H01L 21/60**; **H01L 21/56**; **H01L 23/498**; **H01L 21/48**

## IPC 8 full level

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## CPC (source: EP KR US)

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## Citation (search report)

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